

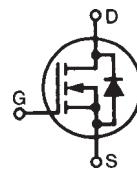
HiperFET™
Power MOSFET
Q3-Class

(Electrically Isolated Tab)

N-Channel Enhancement Mode
Fast Intrinsic Rectifier

IXFR24N100Q3

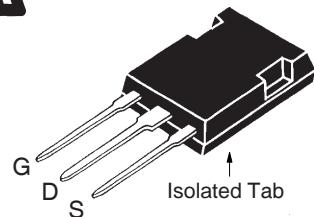
V_{DSS} = 1000V
I_{D25} = 18A
R_{DS(on)} ≤ 490mΩ
t_{rr} ≤ 300ns



ISOPLUS247



®



G = Gate D = Drain
S = Source

Symbol	Test Conditions	Maximum Ratings	
V _{DSS}	T _J = 25°C to 150°C	1000	V
V _{DGR}	T _J = 25°C to 150°C, R _{GS} = 1MΩ	1000	V
V _{GSS}	Continuous	±30	V
V _{GSM}	Transient	±40	V
I _{D25}	T _C = 25°C	18	A
I _{DM}	T _C = 25°C, Pulse Width Limited by T _{JM}	60	A
I _A	T _C = 25°C	24	A
E _{AS}	T _C = 25°C	2	J
dv/dt	I _S ≤ I _{DM} , V _{DD} ≤ V _{DSS} , T _J ≤ 150°C	50	V/ns
P _D	T _C = 25°C	500	W
T _J		-55 ... +150	°C
T _{JM}		150	°C
T _{stg}		-55 ... +150	°C
T _L	1.6mm (0.062 in.) from Case for 10s	300	°C
T _{sold}	Plastic Body for 10s	260	°C
V _{ISOL}	50/60 Hz, 1 Minute	2500	V~
F _c	Mounting Force	20..120/4.5..27	N/lb.
Weight		5	g

Symbol	Test Conditions (T _J = 25°C Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
BV _{DSS}	V _{GS} = 0V, I _D = 1mA	1000		V
V _{GS(th)}	V _{DS} = V _{GS} , I _D = 4mA	3.5		V
I _{GSS}	V _{GS} = ±30V, V _{DS} = 0V			±200 nA
I _{DSS}	V _{DS} = V _{DSS} , V _{GS} = 0V T _J = 125°C		25 μA 1.5 mA	
R _{DS(on)}	V _{GS} = 10V, I _D = 12A, Note 1			490 mΩ

Features

- Silicon Chip on Direct-Copper Bond (DCB) Substrate
- Isolated Mounting Surface
- Low Intrinsic Gate Resistance
- 2500V~ Electrical Isolation
- Fast Intrinsic Rectifier
- Avalanche Rated
- Low Package Inductance

Advantages

- High Power Density
- Easy to Mount
- Space Savings

Applications

- DC-DC Converters
- Battery Chargers
- Switch-Mode and Resonant-Mode Power Supplies
- DC Choppers
- Temperature and Lighting Controls

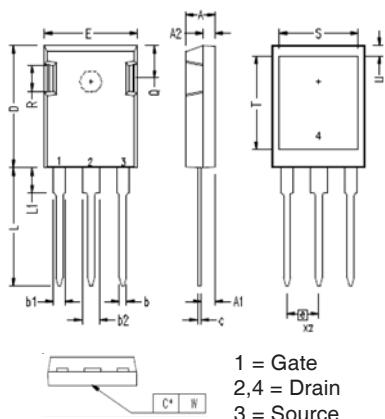
Symbol	Test Conditions (T _J = 25°C Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
g_{fs}	V _{DS} = 20V, I _D = 12A, Note 1	14	24	S
C_{iss}	V _{GS} = 0V, V _{DS} = 25V, f = 1MHz	7200		pF
C_{oss}		590		pF
C_{rss}		50		pF
R_{Gi}	Gate Input Resistance	0.18		Ω
t_{d(on)}	Resistive Switching Times V _{GS} = 10V, V _{DS} = 0.5 • V _{DSS} , I _D = 12A R _G = 1Ω (External)	38		ns
t_r		24		ns
t_{d(off)}		45		ns
t_f		14		ns
Q_{g(on)}	V _{GS} = 10V, V _{DS} = 0.5 • V _{DSS} , I _D = 12A	140		nC
Q_{gs}		47		nC
Q_{gd}		60		nC
R_{thJC}			0.25 °C/W	
R_{thCS}		0.15		°C/W

Source-Drain Diode

Symbol	Test Conditions (T _J = 25°C Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
I_s	V _{GS} = 0V		24	A
I_{SM}	Repetitive, Pulse Width Limited by T _{JM}		96	A
V_{SD}	I _F = I _S , V _{GS} = 0V, Note 1		1.4	V
t_{rr}	I _F = 12A, -di/dt = 100A/μs V _R = 100V, V _{GS} = 0V		300	ns
Q_{RM}		1.9		μC
I_{RM}		12.4		A

Note 1. Pulse test, t ≤ 300μs, duty cycle, d ≤ 2%.

ISOPLUS247 (IXFR) Outline



SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.190	.205	4.83	5.21
A1	.090	.100	2.29	2.54
A2	.075	.085	1.91	2.16
b	.045	.055	1.14	1.40
b1	.075	.085	1.91	2.15
b2	.115	.126	2.92	3.20
C	.024	.033	0.61	0.83
D	.819	.840	20.80	21.34
E	.620	.635	15.75	16.13
e	.215 BSC		5.45 BSC	
L	.780	.801	19.81	20.60
L1	.150	.172	3.81	4.38
Q	.220	.244	5.59	6.20
R	.170	.191	4.32	4.85
S	.520	.540	13.21	13.72
T	.620	.640	15.75	16.26
U	.065	.080	1.65	2.03
W	0	.004	0	0.10

ADVANCE TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065 B1 6,683,344 6,727,585 7,005,734 B2 7,157,338B2 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 6,710,405 B2 6,759,692 7,063,975 B2 4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6,771,478 B2 7,071,537

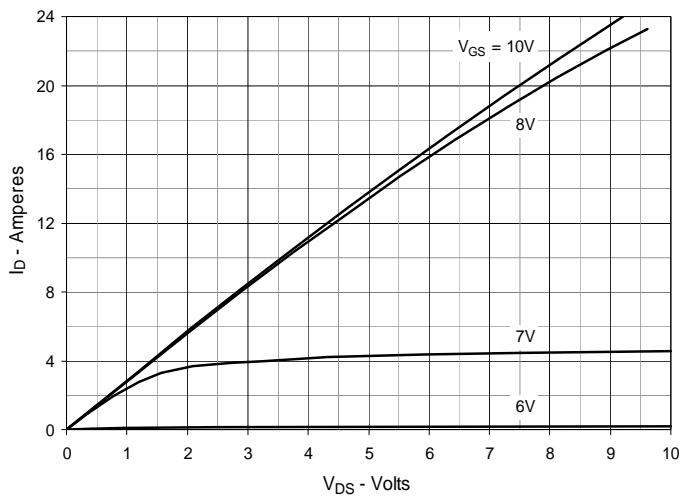
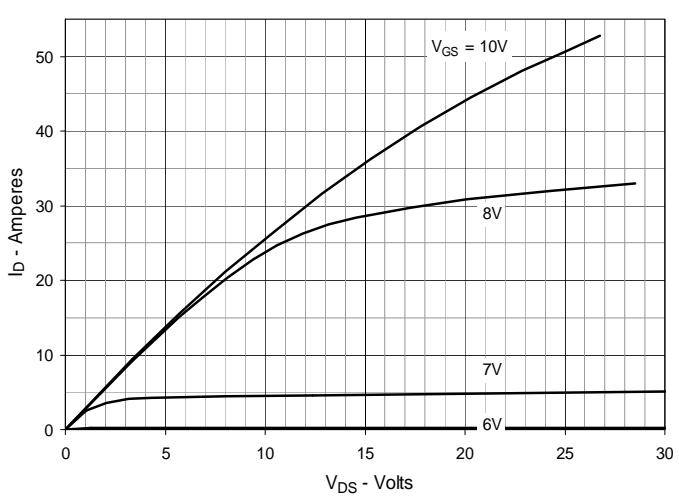
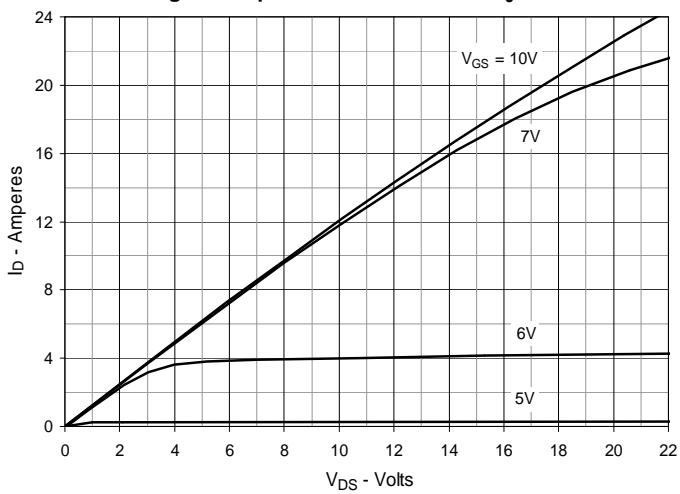
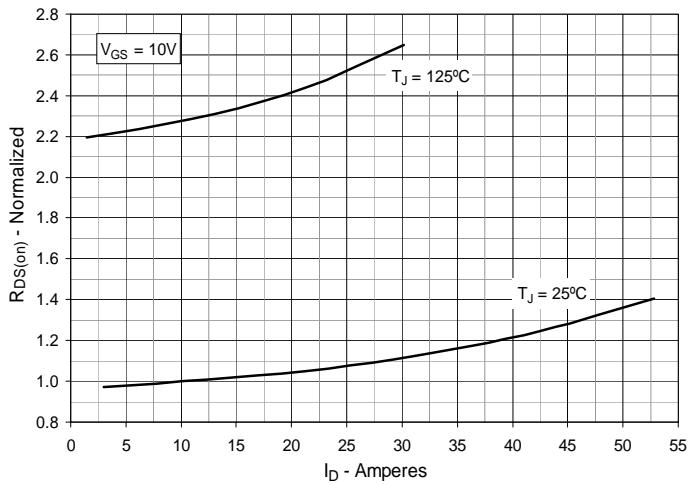
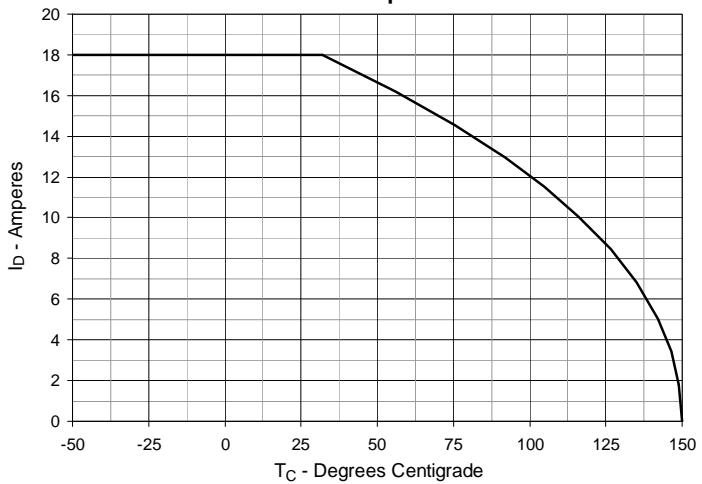
Fig. 1. Output Characteristics @ $T_J = 25^\circ\text{C}$ **Fig. 2. Extended Output Characteristics @ $T_J = 25^\circ\text{C}$** **Fig. 3. Output Characteristics @ $T_J = 125^\circ\text{C}$** **Fig. 5. $R_{DS(on)}$ Normalized to $I_D = 12\text{A}$ Value vs. Drain Current****Fig. 6. Maximum Drain Current vs. Case Temperature**

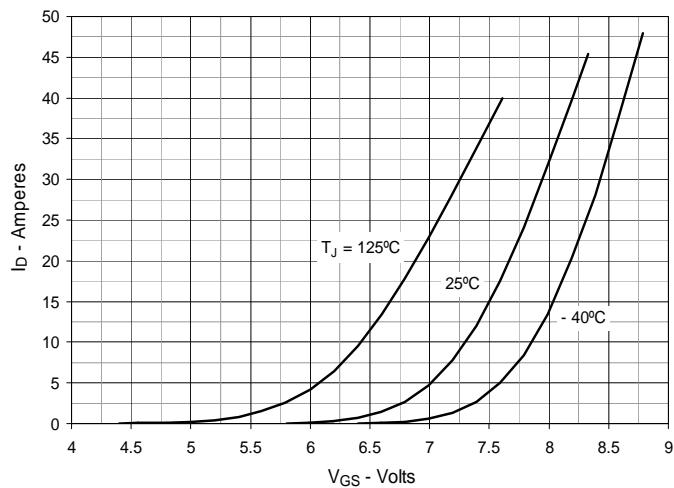
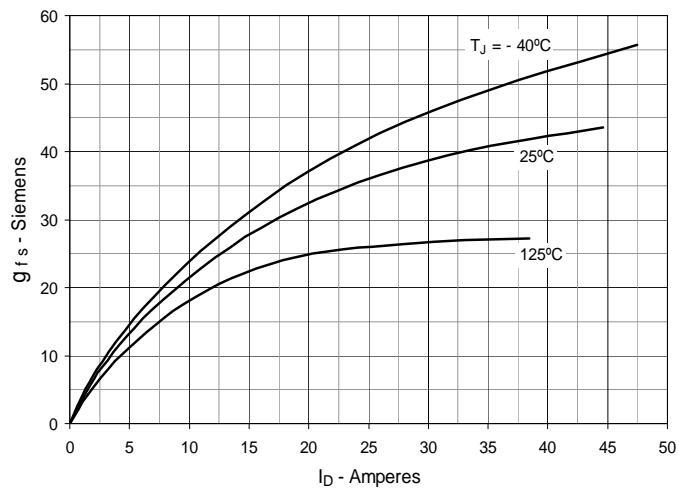
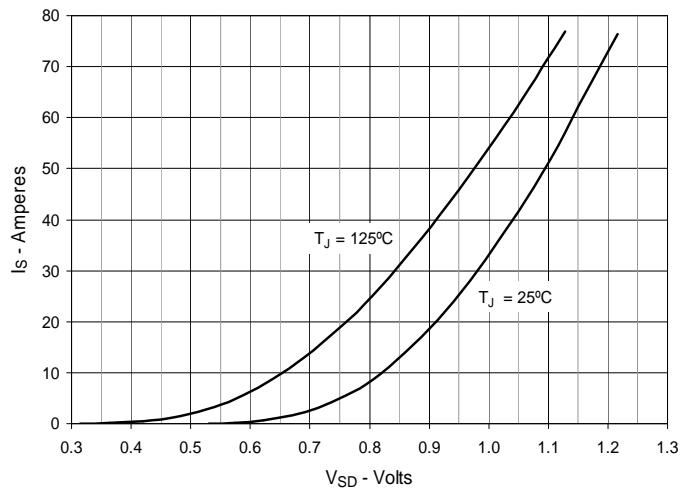
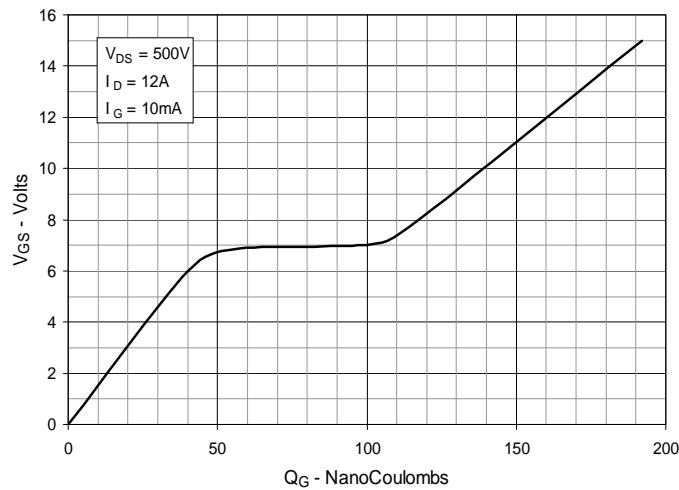
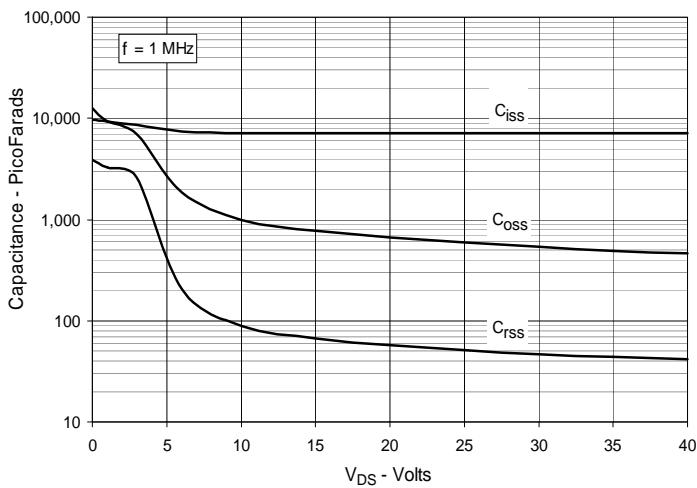
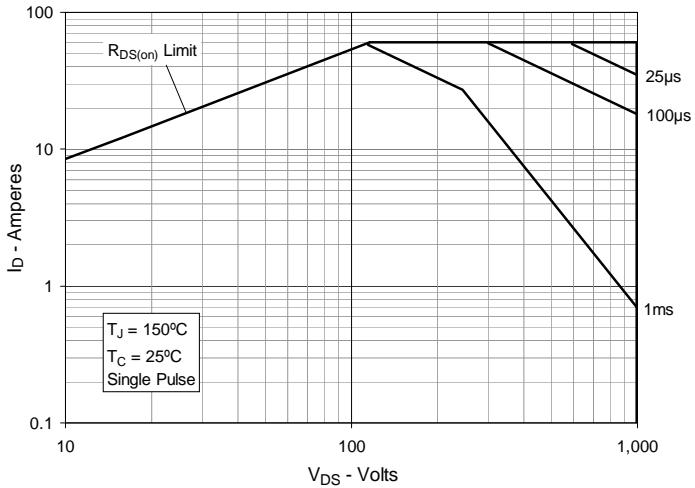
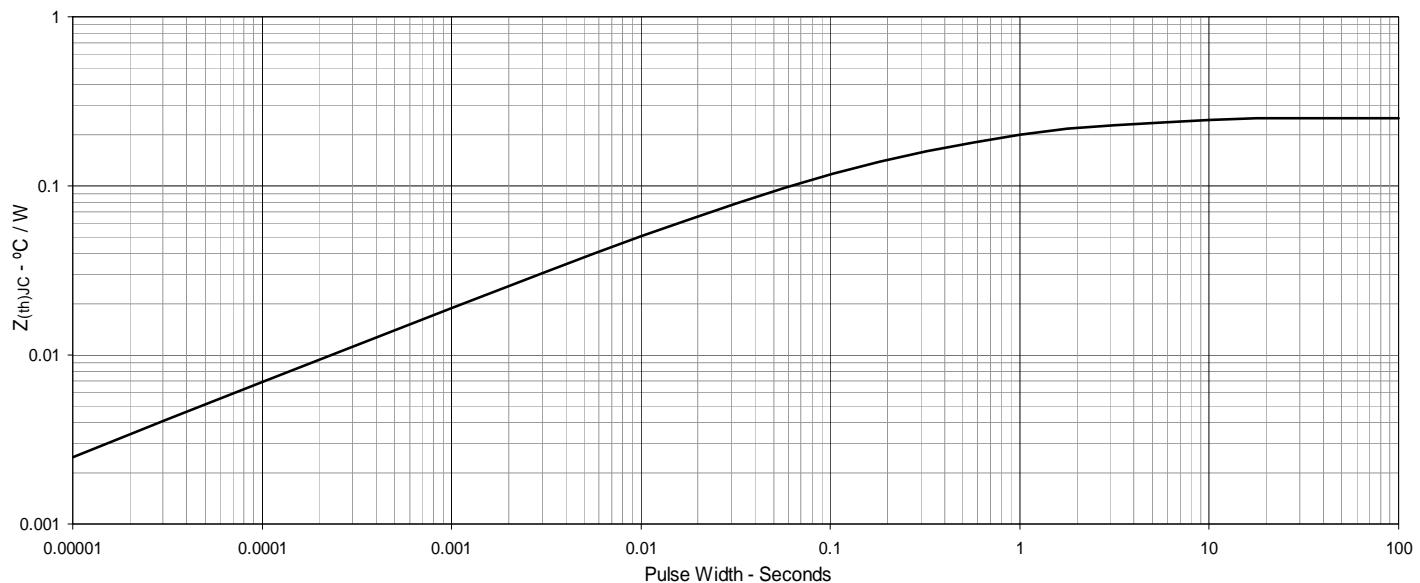
Fig. 7. Input Admittance**Fig. 8. Transconductance****Fig. 9. Forward Voltage Drop of Intrinsic Diode****Fig. 10. Gate Charge****Fig. 11. Capacitance****Fig. 12. Forward-Bias Safe Operating Area**

Fig. 13. Maximum Transient Thermal Impedance

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